

O I P E JC98  
JUL 24 2002  
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **YONEDA, et al.**

Group Art Unit: **2814**

Serial No.: **09/442,038**

Examiner: **N. Ha**

Filed: **November 17, 1999**

For: **DEVICE HAVING RESIN PACKAGE AND METHOD OF PRODUCING THE SAME**

**RESPONSE UNDER 37 CFR §1.116**

**- EXPEDITED RESPONSE -  
GROUP ART UNIT 2814**

**BOX AF**

Commissioner for Patents  
Washington, D.C. 20231

July 24, 2002

Sir:

In response to the Office Action dated **April 19, 2002**, extended to **August 19, 2002** by a 1 month Petition for Extension of Time, please amend the above-identified application as follows:

**IN THE CLAIMS:**

Amend claim 34 as follows:

34. (Amended) A device comprising:

a chip;

a resin package sealing said chip, said resin package having a mount-side surface of the resin package which comprises a resin tape;

metallic films respectively provided in the resin package so that the metallic films are flush with the mount-side surface and are exposed therefrom; and

connecting parts electrically connecting electrode pads of said chip and the metallic films.